



*JPW*

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Dated: February 20, 2007

Signature:

*[Signature]*  
(William P. O'Sullivan)

Docket No.: TESSERA 3.0-395  
(PATENT)

IN THE UNITED STATES PATENT AND TRADEMARK OFFICE

In re Patent Application of:  
Humpston et al.

Application No.: 10/711,945

Filed: October 14, 2004

For: WAFER LEVEL MICROELECTRONIC  
PACKAGING WITH DOUBLE ISOLATION

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: Group Art Unit: 2878  
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: Examiner: S. K. Yam  
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Commissioner for Patents  
P.O. Box 1450  
Alexandria, VA 22313-1450

RESPONSE

In response to the official action mailed November 20, 2006, applicants submit the following remarks.